

Customer No.: 31561  
Application No.: 10/604,744  
Docket No.: 9720-US-PA

REMARKS

Present Status of the Application

The Office Action has considered the present invention in four species, as referred to FIG. 2, FIG. 3, FIG. 4, and FIG. 5. Applicant respectfully traverses the restriction requirement and has preliminarily elected Specie I for claims 1-6 being currently examined.

However, Applicant believes that the four species recite the common features, and should be considered as the same invention. Claims 1-20 remain pending in the present application, and reconsideration of those claims is respectfully requested.

Discussion of Restrictions

Applicant has responded to the Office Action by electing claims 1-6, with respect to FIG. 2, for examination. However, Applicant respectfully requests that the features in whole application relating to FIG. 2, FIG. 3, FIG. 4, and FIG. 5 should be consider as the same invention.

As shown in FIGs. 2-5, the common features include the side circuit formed on the sidewall of the laminated layer. Under these features, the side circuit can have several embodiments in design option, so that at least two patterned circuit layer can be connected.

Further, the laminated layer may have the cavity or opening. Then, the sidewall can be referred to the actual sidewall at the periphery of the laminate layer or the sidewall of the cavity. The side circuit can then be formed on sidewalls of the cavity. Therefore, the sidewall of the

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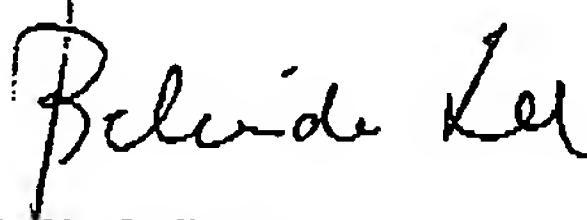
cavity should be considered as the same inventions but in different embodiments.

As mentioned above, the laminated layer may or may not have the cavity. But, this cavity is the alternative option and should also be considered the different embodiment of the same invention.

For at least the foregoing reasons, Applicant respectfully requests that the features in FIGs. 2-5 be considered as the same invention in different embodiments.

Respectfully submitted,

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